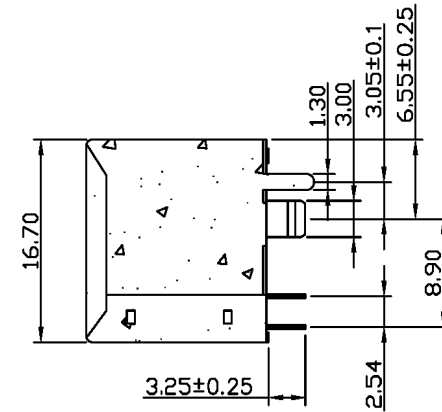
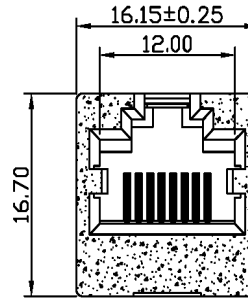


PC Board Layout



SPECIFICATIONS

Contact material: Phosphor bronze 0.35mm

Contact plating: Gold 15µ" in contact area

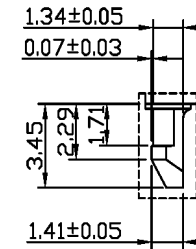
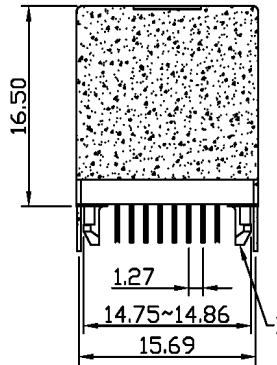
Tin in solder area

Housing material: PBT with 15% glass fiber, UL94V-0

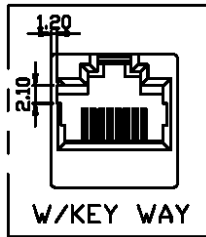
Shield material: Copper alloy 0.25mm

Shield plating: Tin

Options: Available with key way



DETAIL X



W/KEY WAY

RoHS compliant

Series	Positions	Contacts	Body	Ground Tab	Color	Plating	Options
CTJ	8	08	XX	C1	BK	XX	XX
Modular phone jack	8=8 positions	08=8 contacts	DS=Top Entry DSHP=Top Entry Half Peg	C1=3.05mm Front	BK=Black	P1=15µ" gold P2=30µ" gold P3=50µ" gold	FS=Full shield WF=Without flange KY=With key way

Rev.	Description	Date	Approved	Drawing	Name	Date
				Approved	Howard	08/10/99
				Checked	Lizzy	08/10/99
				Drawn	Tina	08/10/99
		0.0 ± 0.35	0.00 ± 0.20	Angles ± 3°		
				UNIT: mm		

Central Components Manufacturing
 440 Lincoln Blvd., Middlesex, New Jersey 08846
 Phone 732 469-5720 888 288-5152 Fax 732 469-1919

Part No.: **CTJ-8-08-DSHP-C1-BK-XX-FS-WF**

Description: Modular jack, 8P8C, shielded, top entry, no flange